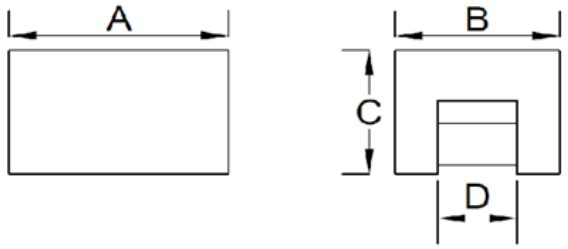
High Current Ferrite Bead

BPH322521W5-350T

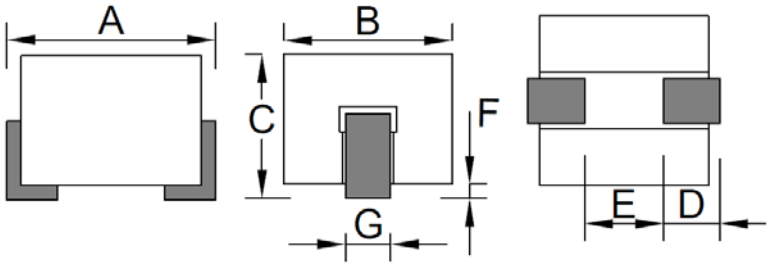
1. Features

1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
2. Operating temperature -40~+125℃ (Including self - temperature rise)

2. Dimension



CORE SIZE			
A(mm)	B(mm)	C(mm)	D(mm)
3.10±0.15	2.50±0.15	2.10±0.15	0.90±0.15



PRODUCT SIZE						
A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
3.10±0.15	2.50±0.15	2.15±0.15	0.85±0.20	1.20±0.20	0.00～0.10	0.70±0.10

3. Part Numbering

BPH	322521	W5	-	350	T
A	B	C		D	E

A: Series
B: Dimension
C: Material Ferrite Core
D: Impedance 350=35Ω
E: Packaging T=Taping and Reel

4. Specification

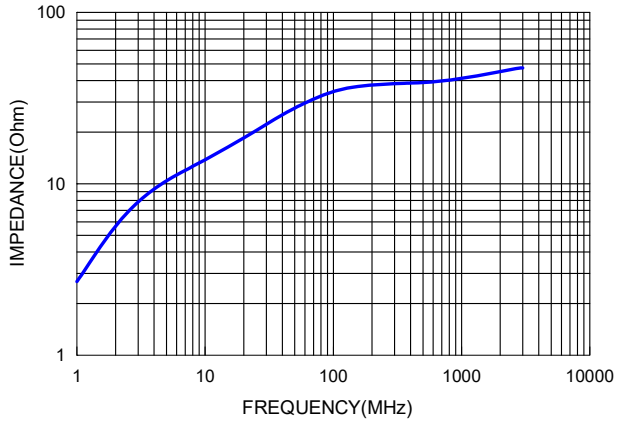
TAI-TECH Part Number	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR (mΩ) Max.	Rated Current(A)
	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)		△T=40℃ TYP.
BPH322521W5-350T	25	±25	25	35	±25	100	0.60	21.0

Note:

Rated Current:

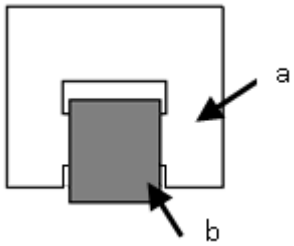
(1) : Chroma high current test fixture.

Typical Impedance v.s. Frequency Curve

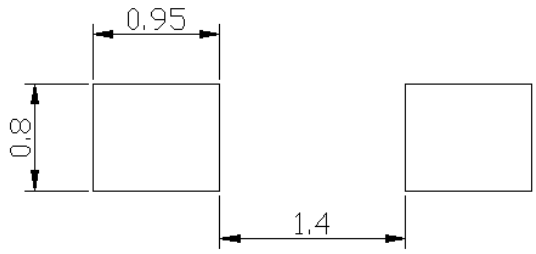


5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire



6. Recommended PC Board Pattern



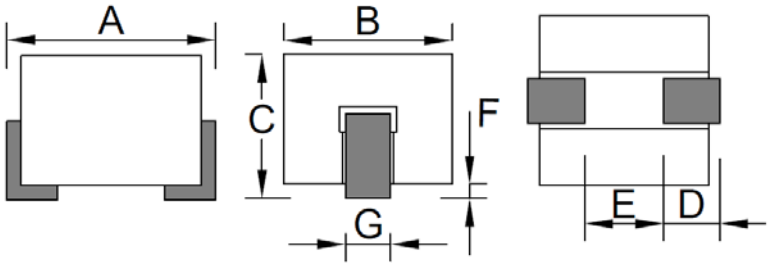
High Current Ferrite Bead

BPH323023W5-400T

1. Features

1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
2. Operating temperature-40~+125℃ (Including self - temperature rise)

2. Dimension



PRODUCT SIZE						
A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
3.08 +0.10/-0.15	2.90±0.10	2.20±0.10	0.80±0.20	1.20 Min.	0.00～0.11	0.85±0.10

3. Part Numbering

BPH	323023	W5	-	400	T
A	B	C		D	E

A: Series
B: Dimension
C: Material — Ferrite Core
D: Impedance — 400=40Ω
E: Packaging — T=Taping and Reel

4. Specification

TAI-TECH Part Number	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR (mΩ) Max.	Rated Current(A)	
	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)		△T=40℃ TYP.	△T=60℃ TYP.
BPH323023W5-400T	23	±25	25	40	±25	100	0.60	21.0(1) 15.0(2)	26.0(1) 18.0(2)

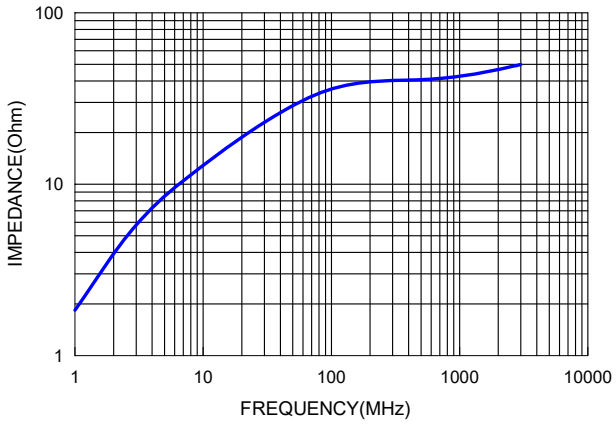
Note:

Rated Current :

(1) : Chroma high current test fixture.

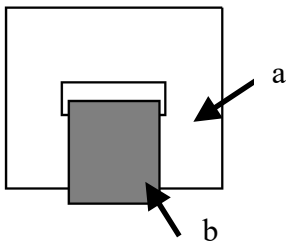
(2) :PCB test fixture (30x45mm copper pattern , 50um copper thickness).

Typical Impedance v.s. Frequency Curve

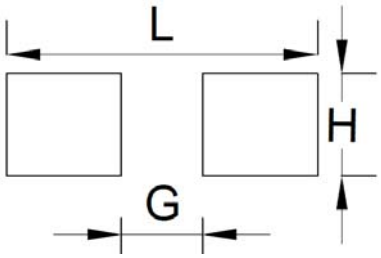


5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire (0.8W X 0.25T)mm



6. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)
3.70	1.10	1.10

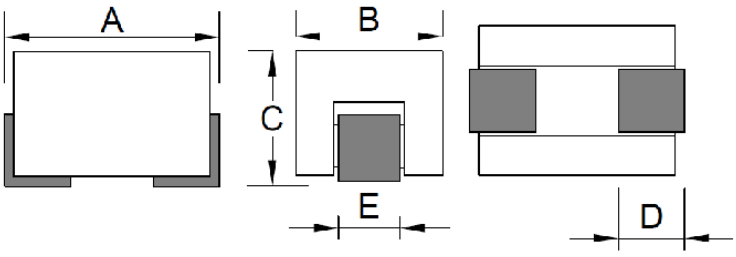
High Current Ferrite Bead

BPH403022R5-400T-G

1. Features

1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
2. Operating temperature -40~+125℃ (Including self - temperature rise)

2. Dimension



PRODUCT SIZE				
A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
3.90～4.50	3.00±0.15	2.20 Max	1.00±0.20	1.25±0.15

3. Part Numbering

BPH	403022	R5	-	400	T	-	G
A	B	C		D	E		F

A: Series
B: Dimension
C: Material — Ferrite Core
D: Impedance — 400=40Ω
E: Packaging — T=Taping and Reel
F: Control S/N

4. Specification

TAI-TECH Part Number	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR (mΩ) Max.	Rated Current(A)	
	Impedance (Ω)	Tolerance (%)	Test Frequency (Hz)	Impedance (Ω)	Tolerance (%)	Test Frequency (Hz)		△T=40℃ TYP.	△T=60℃ TYP.
BPH403022R5-400T-G	24	±25	25M	40	±25	100M	0.7	20.0	28.0

Note:

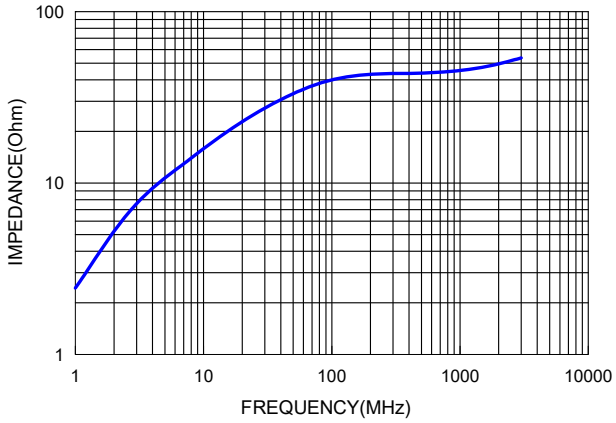
Rated Current :

(1) : Chroma high current test fixture.

(2) : DCR is measured on a micro-ohmmeter at points indicat in the diagram.

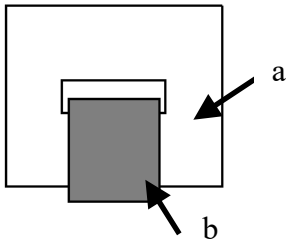


Typical Impedance v.s. Frequency Curve

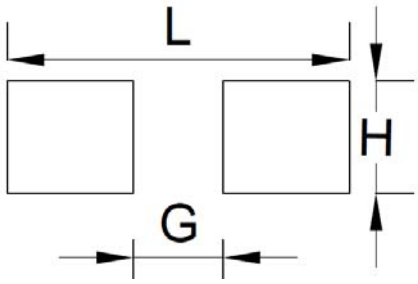


5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire (1.25W X 0.21T)m/m



6. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)
4.8	2.0	1.5

High Current Ferrite Bead

BPH403025R5-530T

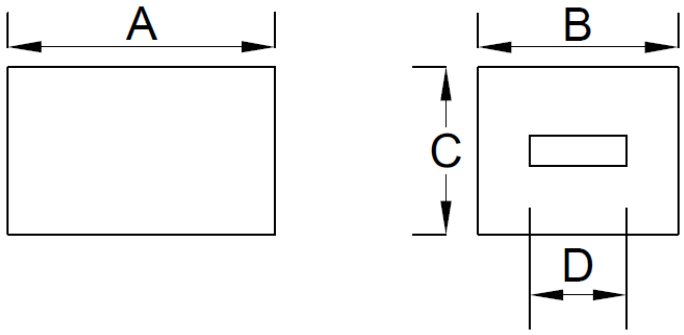
1. Features

1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
2. Operating temperature-40~+125℃ (Including self - temperature rise)

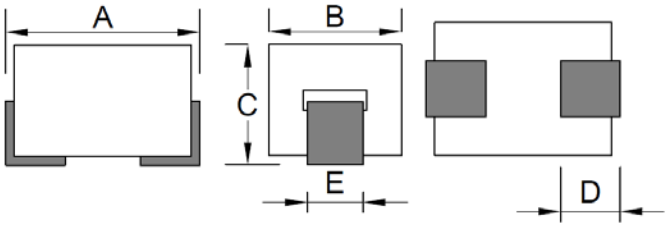
Halogen-free

RoHS

2. Dimension



CORE SIZE			
A(mm)	B(mm)	C(mm)	D(mm)
4.00±0.25	3.10±0.15	2.50±0.15	1.50±0.15



PRODUCT SIZE				
A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
4.30～5.10	3.10±0.15	2.70～3.1	1.35±0.20	1.35±0.15

3. Part Numbering

BPH	403025	R5	-	530	T
A	B	C		D	E

A: Series
B: Dimension
C: Material — Ferrite Core
D: Impedance — 530=53Ω
E: Packaging — T=Taping and Reel

4. Specification

TAI-TECH Part Number	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR (mΩ) Max.	Rated Current(A)	
	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)		△T=40℃ TYP.	△T=60℃ TYP.
BPH403025R5-530T	35	±25	25	53	±25	100	0.60	35.0(1) 15.0(2)	45.0(1) 18.0(2)

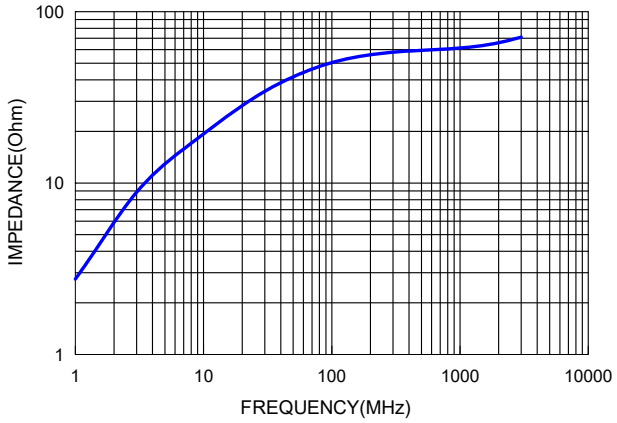
Note:

Rated Current :

(1) : Chroma high current test fixture.

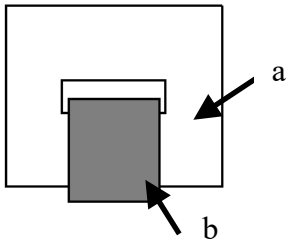
(2) :PCB test fixture (30x45mm copper pattern , 50um copper thickness).

Typical Impedance v.s. Frequency Curve

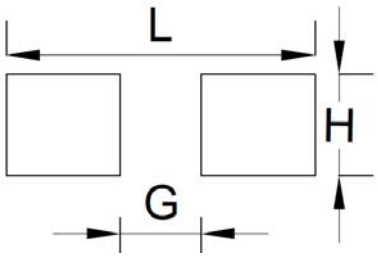


5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire (1.25W X 0.21T)m/m



6. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)
4.8	1.4	1.5

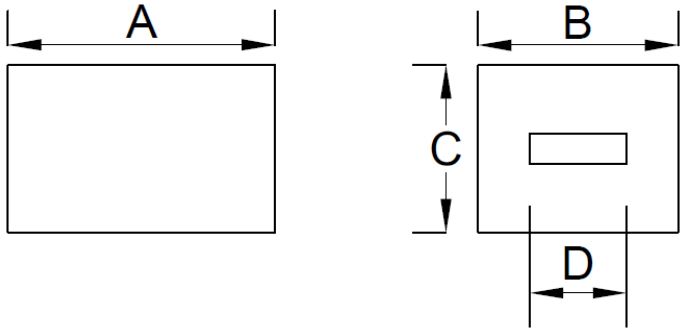
High Current Ferrite Bead

BPH403025MN5-470TP

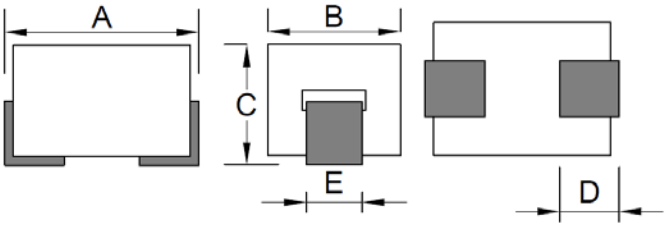
1. Features

1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
2. Operating temperature -40~+125℃ (Including self - temperature rise)

2. Dimension



CORE SIZE			
A(mm)	B(mm)	C(mm)	D(mm)
4.00±0.25	3.10±0.15	2.50±0.15	1.50±0.15



PRODUCT SIZE				
A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
4.30～5.10	3.10±0.15	2.70～3.10	1.35±0.20	1.35±0.15

3. Part Numbering

BPH	403025	MN5	-	470	T	P
A	B	C		D	E	F

A: Series
B: Dimension
C: Material — MnZn Core
D: Impedance — 470=47Ω
E: Packaging — T=Taping and Reel
F: Surface coating — Parylene coating

4. Specification

TAI-TECH Part Number	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR (mΩ) Max.	Rated Current(A)	
	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)		△T=40℃ TYP.	△T=60℃ TYP.
BPH403025MN5-470TP	20	±25	1	47	±25	10	0.75	24.0(1) 10.0(2)	28.0(1) 13.0(2)

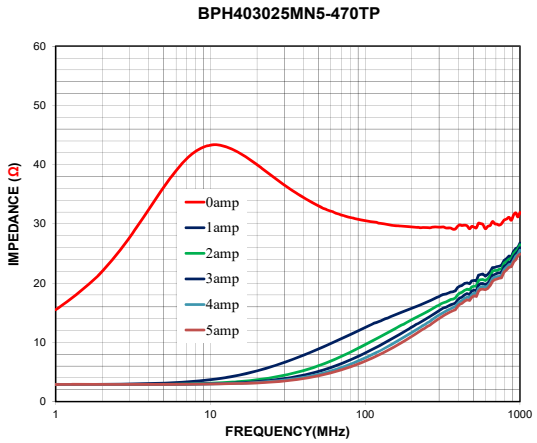
Note:

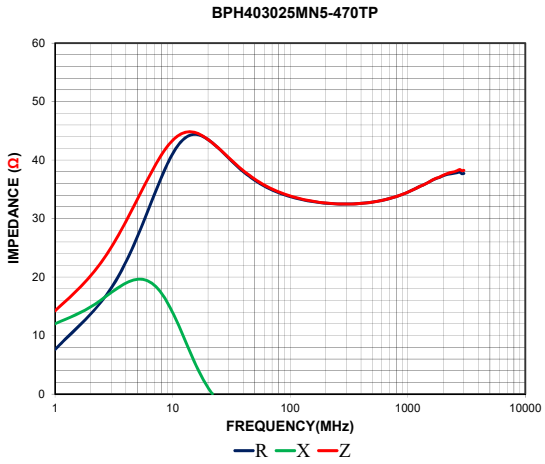
Rated Current :

(1) : Chroma high current test fixture.

(2) :PCB test fixture (30x45mm copper pattern , 50um copper thickness).

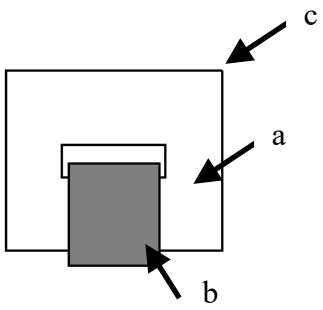
Typical Impedance v.s. Frequency Curve



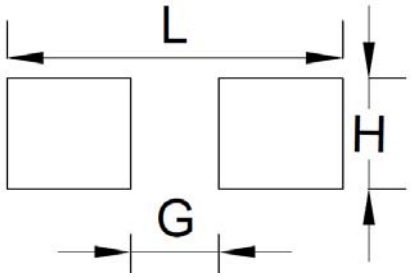


5. Material List

No.	Description	Specification
a.	Core	MnZn Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire (1.25W X 0.21T)m/m
c	Surface coating	Parylene coating



6. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)
4.8	1.4	1.5

High Current Ferrite Bead

BPH853025R5-101T

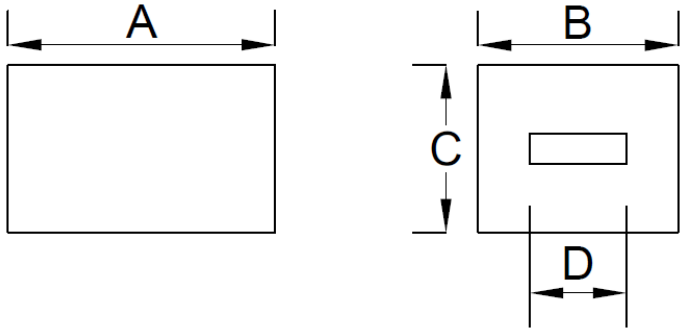
1. Features

1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
2. Operating temperature -40~+125℃ (Including self - temperature rise)

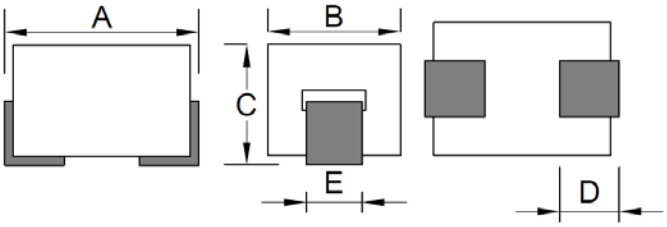
Halogen-free

RoHS

2. Dimension



CORE SIZE			
A(mm)	B(mm)	C(mm)	D(mm)
8.50±0.25	3.00±0.15	2.50±0.15	1.50±0.15



PRODUCT SIZE				
A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
9.00±0.40	3.00±0.15	2.80±0.25	1.50±0.50	1.25±0.20

3. Part Numbering

BPH	853025	R5	-	101	T
A	B	C		D	E

A: Series
B: Dimension
C: Material — Ferrite Core
D: Impedance — 101=100Ω
E: Packaging — T=Taping and Reel

4. Specification

TAI-TECH Part Number	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR (mΩ) Max.	Rated Current(A)	
	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)		△T=40℃ TYP.	△T=60℃ TYP.
BPH853025R5-101T	65	±25	25	100	±25	100	1.00	30(1) 13(2)	40(1) 18(2)

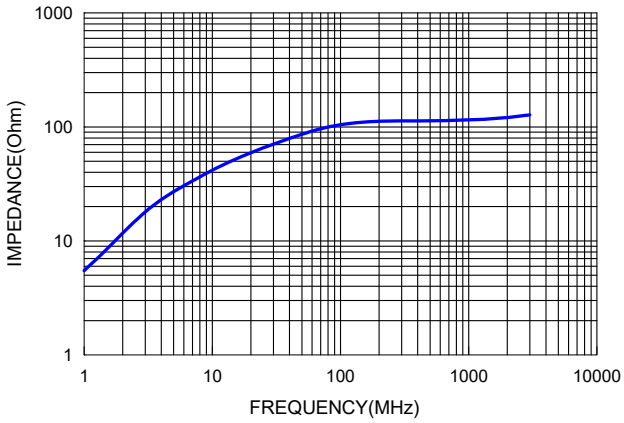
Note:

Rated Current :

(1) : Chroma high current test fixture.

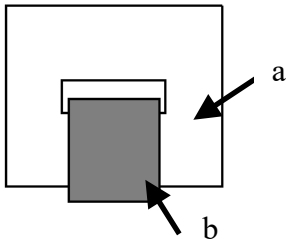
(2) :PCB test fixture (30x45mm copper pattern , 50um copper thickness).

Typical Impedance v.s. Frequency Curve

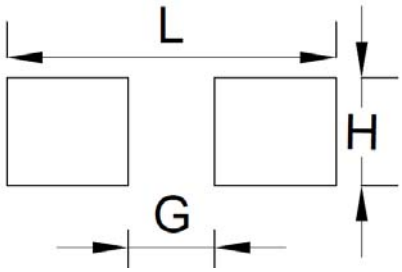


5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire (1.25W X 0.21T)m/m



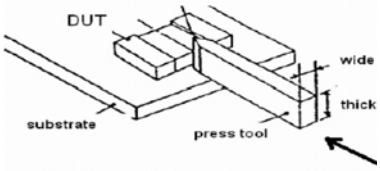
6. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)
10.7	4.5	1.5

Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance Test		
Z(Impedance)	Refer to standard electrical characteristics list.	Agilent E4991A + Keysight 16092A
DCR		Agilent-34420A
Heat Rated Current (Irms)	Approximately △T≦40℃	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃) without core loss. 1.Applied the allowed DC current(keep 1 min.). 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage. Impedance：within±15% of initial value RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature： 125±2℃(Inductor) Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24 hrs.
Load Humidity		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Humidity：85±3% R.H, Temperature：85℃±2℃ Duration：1000hrs Min. Bead：with 100% rated current，Inductance: with 10% rated current Measured at room temperature after placing for 24 hrs.
Moisture Resistance		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1：-40±2℃ 30±5min Step2：125±2℃ ≦0.5min Step3：125±2℃ 30±5min Number of cycles： 500 Measured at room temperature after placing for 24 hrs
Vibration		Oscillation Frequency: 10Hz～2KHz～10Hz for 20 minute Equipment： Vibration checker Total Amplitude:10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。

<table>
<tr><th>Item</th><th>Performance</th><th>Test Condition</th></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth: >=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td>
<table>
<tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr>
<tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
<tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
</table>
3 shocks in each direction along 3 perpendicular axes. (18 shocks).
</td></tr>
<tr><td>Solderability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>a. Method B, 4 hrs @155°C dry heat @235°C±5°C
Testing Time :5 +0/-0.5 seconds
b. Method D category 3. (8hours ± 15 min)@ 260°C±5°C
Testing Time :30 +0/-0.5 seconds</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
RDC：within ±15% of initial value and shall not exceed the specification value e</td><td>Depth: completely cover the termination
<table>
<tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr>
<tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr>
</table>
</td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles
With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.


</td></tr>
</table>

Soldering and Mounting

1-1. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

1-1.1 Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

1-1.2 Solder Wave:

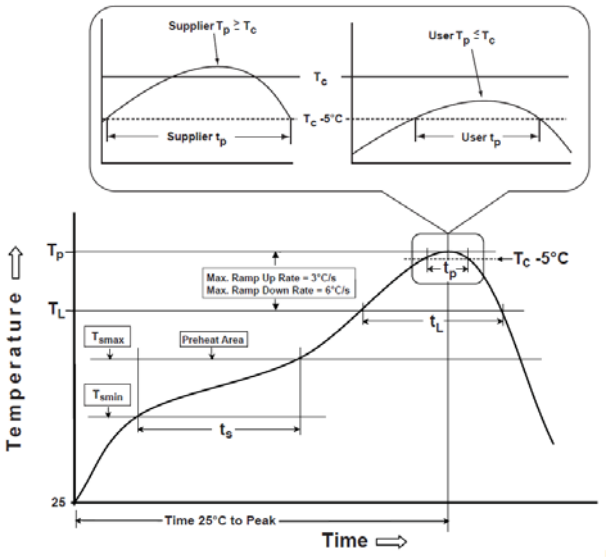
Wave soldering is perhaps the most rigorous of surface mount soldering processes due to the steep rise in temperature seen by the circuit when immersed in the molten solder wave, Due to the risk of thermal damage to products, wave soldering of large size products is discouraged. Recommended temperature profile for wave soldering is shown in Figure 3.

1-1.3 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

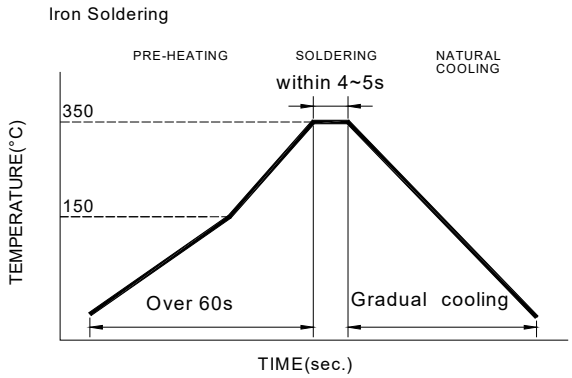
- Preheat circuit and products to 150℃
- 350℃ tip temperature (max)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron soldering temperature profiles



Iron Soldering times：1 times max

Fig.3 Wave Soldering

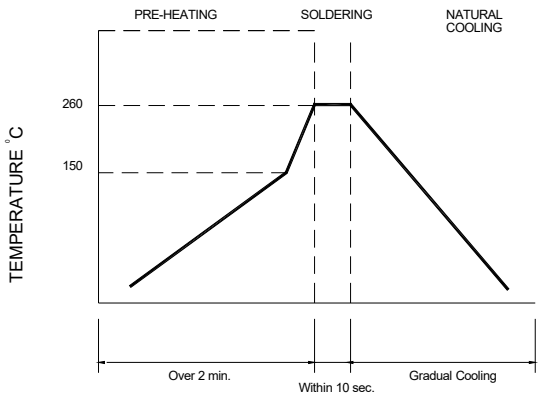


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	 150℃ 200℃ 60-120seconds
Ramp-up rate($T_L$to T_p)	3℃/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217℃ 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at Tc- 5℃ (Tp should be equal to or less than Tc.)	< 30 seconds
Ramp-down rate(T_p to T_L)	6℃ /second max.
Time 25℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

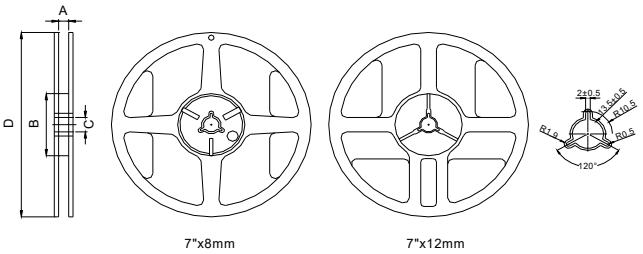
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	260℃	260℃	260℃
	1.6-2.5mm	260℃	250℃	245℃
	≥2.5mm	250℃	245℃	245℃

Reflow is referred to standard IPC/JEDEC J-STD-020E。

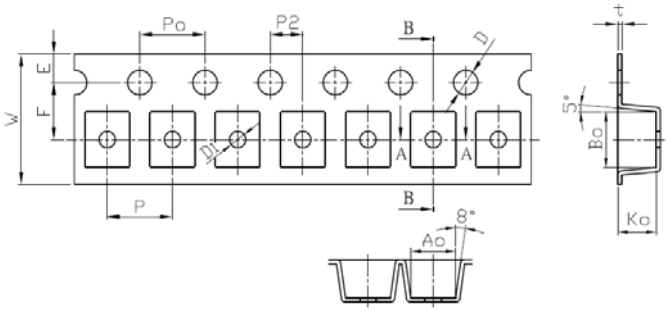
8. Packaging Information

8-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	8.4±1.0	50 min.	13.0±0.8	178.0±2.0

8-2. Tape Dimension / 8mm

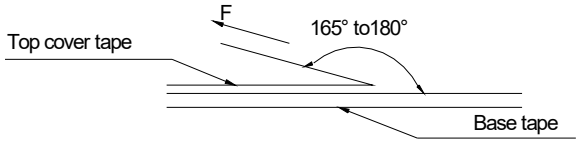


Series	Size	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	D1(mm)	Po(mm)	Ao(mm)	Bo(mm)	Ko(mm)	t(mm)	10Po(mm)
BPH	322521	8.00±0.1	4.00±0.1	1.75±0.1	3.50±0.05	2.00±0.05	1.5+0.1/-0	1.0±0.10	4.00±0.1	2.75±0.1	3.45±0.1	2.35±0.1	0.26±0.05	40.0±0.20

8-3. Packaging Quantity

Chip size	Chip / Reel	Inner box	Middle box	Carton
322521	1000	5000	25000	50000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

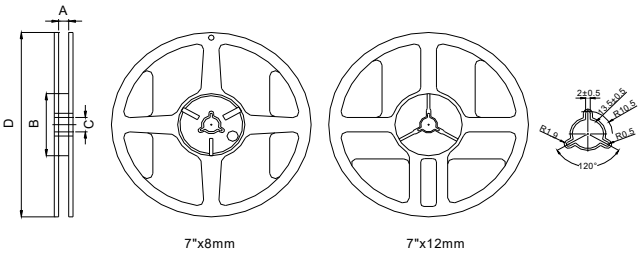
Application Notice

- Storage Conditions(component level)
  To maintain the solderability of terminal electrodes:
  1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

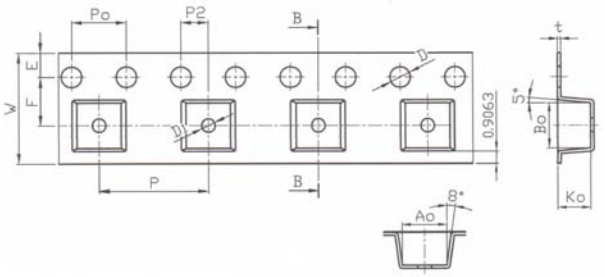
8. Packaging Information

8-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x12mm	13.5±0.5	60.0±2.0	13.5±0.5	178.0±2.0

8-2. Tape Dimension / 12mm

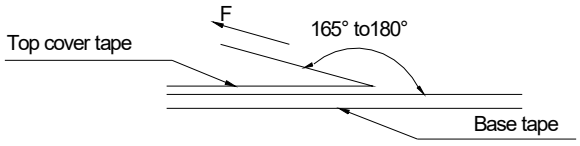


Series	Size	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	D1(mm)	Po(mm)	Ao(mm)	Bo(mm)	Ko(mm)	t(mm)	10Po(mm)
BPH	323023	12.00±0.1	8.00±0.1	1.75±0.1	5.50±0.05	2.00±0.05	1.5+0.1/-0	1.5±0.10	4.00±0.1	3.5±0.1	3.35±0.1	2.40±0.1	0.30±0.05	40.0±0.20

8-3. Packaging Quantity

Chip size	Chip / Reel	Inner box	Middle box	Carton
323023	1000	4000	20000	40000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

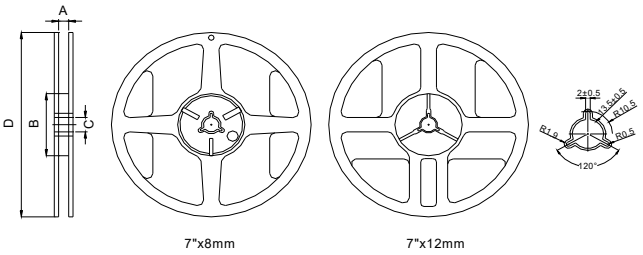
Application Notice

- Storage Conditions(component level)
  To maintain the solderability of terminal electrodes:
  1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

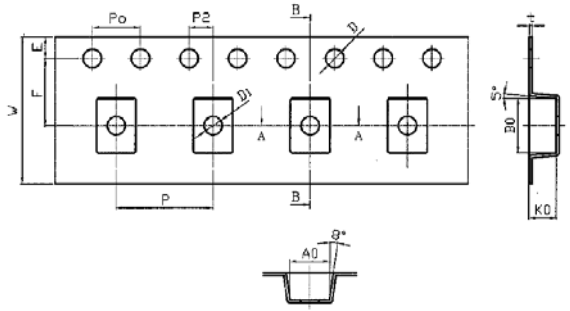
8. Packaging Information

8-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x12mm	13.5±0.5	60.0±2.0	13.5±0.5	178.0±2.0

8-2. Tape Dimension /12mm

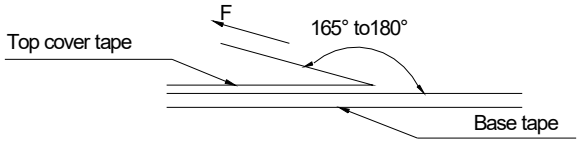


Series	Size	W(mm)	P(mm)	E(mm)	F(mm)	Po(mm)	P2(mm)	D(mm)	D1(mm)	Ao(mm)	Bo(mm)	Ko(mm)	t(mm)
BPH	403022	12.0.±0.10	8.00±0.10	1.75±0.10	5.50±0.05	4.00±0.10	2.00±0.05	1.50+0.10/-0.00	1.50±0.10	3.25±0.10	4.45±0.10	2.25±0.10	0.24±0.05

8-3. Packaging Quantity

Chip size	Chip / Reel	Inner box	Middle box	Carton
BPH403022	500	2000	10000	20000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

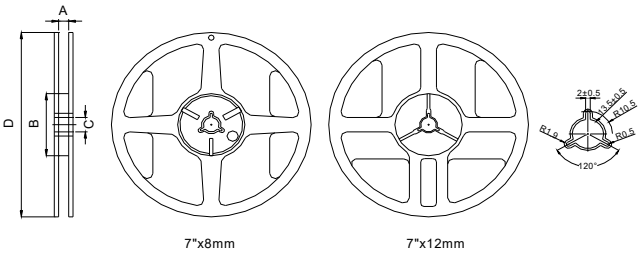
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  2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

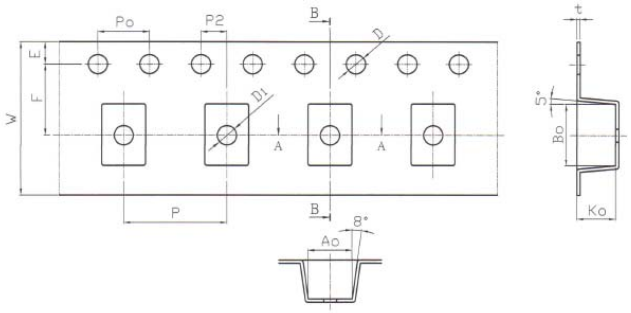
8. Packaging Information

8-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x12mm	13.5±0.5	60.0±2.0	13.5±0.5	178.0±2.0

8-2. Tape Dimension /12mm

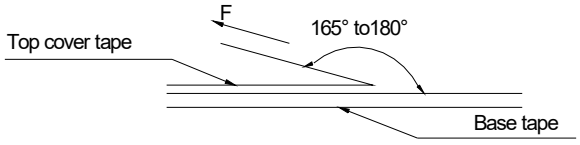


Series	Size	W(mm)	P(mm)	Po(mm)	Ao(mm)	Bo(mm)	Ko(mm)	t(mm)
BPH	403025	12.±0.10	8.0±0.10	4.0±0.10	3.30±0.10	4.8±0.10	3.1±0.10	0.28±0.05

8-3. Packaging Quantity

Chip size	Chip / Reel	Inner box	Middle box	Carton
BPH403025	500	2000	10000	20000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

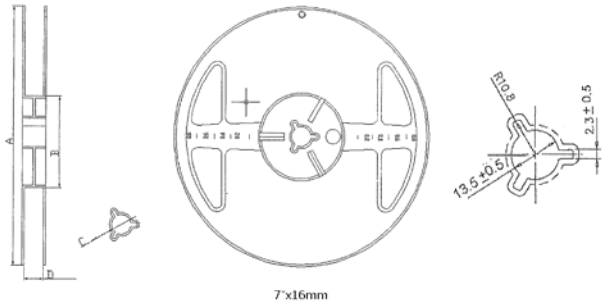
Application Notice

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  To maintain the solderability of terminal electrodes:
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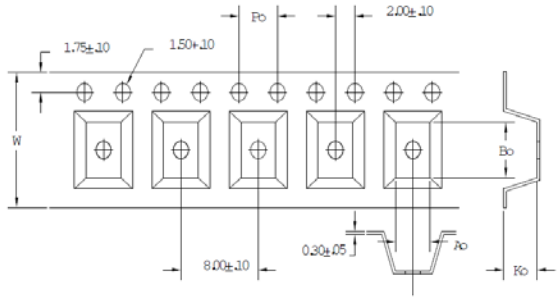
8. Packaging Information

8-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x16mm	178.0±2.0	60.0±2.0	13.5±0.5	16.7±0.5

8-2. Tape Dimension / 16mm

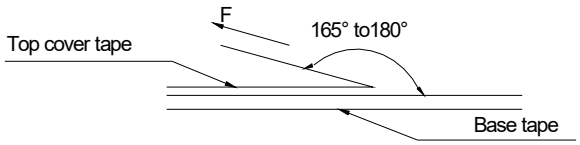


Series	Size	W(mm)	Po(mm)	Ao(mm)	Bo(mm)	Ko(mm)
BPH	853025	16.±0.30	4.0±0.10	3.25±0.10	9.25±0.10	3.05±0.10

8-3. Packaging Quantity

Chip size	Chip / Reel	Inner box	Middle box	Carton
BPH853025	500	2000	10000	20000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions(component level)
  To maintain the solderability of terminal electrodes:
  1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation
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  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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